

## pSEMI MATERIAL DECLARATION FORM

<b>Product:</b>	PE42722
<b>Ordering Codes:</b>	PE42722B-Z
<b>Description:</b>	UltraCMOS® SPDT RF Switch, 5- 1794 MHz
<b>Package:</b>	32L 5x5 QFN
<b>Environmental Compliance</b>	EU RoHS Directive 2011/65/EC and amendment 2015/863, <b>REACH</b> - EU ECHA SVHC, <b>Arsenic Free, JIG 101</b> - EIA/EICTA/JEITA, <b>Halogen Free</b> - IEC61249-2-21, <b>PFOS Free</b> - 2006/122/EC, <b>Antimony Trioxide Free</b>
<b>Lead Finish</b>	NiPdAu
<b>Availability</b>	4/15/2020

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	3.353391	5.09%	50,869.94
Die	Aluminum	7429-90-5	0.010200	0.02%	154.73
Die	Silicon	7440-21-3	0.000680	0.00%	10.32
Die	Arsenic	7440-38-2	0.000003	0.00%	0.05
Die	Boron	7440-42-8	0.000003	0.00%	0.05
Die	Phosphorus	7723-14-0	0.000014	0.00%	0.21
Die	Titanium	7440-32-6	0.001700	0.00%	25.79
Die	Tungsten	7440-33-7	0.034001	0.05%	515.78
Die	Cobalt	7440-48-4	0.000068	0.00%	1.03
Die	Copper	7440-50-8	0.000027	0.00%	0.41
Leadframe	Copper	7440-50-8	26.714000	40.52%	405,243.39
Leadframe	Iron	7439-89-6	0.643900	0.98%	9,767.77
Leadframe	Zinc	7440-66-6	0.032900	0.05%	499.08
Leadframe	Phosphorous	7723-14-0	0.008200	0.01%	124.39
Die Attach	Silver	7440-22-4	0.287200	0.44%	4,356.74
Die Attach	Epoxy Resin	9003-36-5	0.035900	0.05%	544.59
Die Attach	Diluent	26447-14-3	0.021500	0.03%	326.15
Die Attach	Dicyandiamide	461-58-5	0.003600	0.01%	54.61
Die Attach	Hardener	620-92-8	0.010800	0.02%	163.83
Wire	Gold	7440-57-5	0.552900	0.84%	8,387.33
Plating	Others	Proprietary	0.000100	0.00%	1.52
Plating	Nickel	7440-02-0	0.180330	0.27%	2,735.55
Plating	Palladium	7440-05-3	0.014580	0.02%	221.17
Plating	Gold	7440-57-5	0.000580	0.00%	8.80
Molding Compound	Silica Fused	60676-86-0	31.191100	47.32%	473,159.66
Molding Compound	Epoxy Resin	Trade secret	1.360600	2.06%	20,639.90
Molding Compound	Phenol Resin	Trade secret	1.360600	2.06%	20,639.90
Molding Compound	Carbon Black	1333-86-4	0.102000	0.15%	1,547.31
<b>Total Weight (mg)</b>			<b>65.920878</b>	100.00%	1,000,000